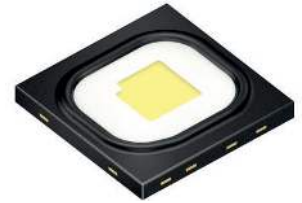


# LUW HWQP

## OSLON® Black Flat

OSLON Black Flat is a new small size high-flux LED for slim designs. The black package stands for high stability.



### Applications

- Architecture
- Custom Tuning
- Headlamps, LED & Laser & Night Vision
- Stage Lighting (LED & Laser)

### Features:

- Package: SMD epoxy package
- Chip technology: UX:3
- Typ. Radiation: 120° (Lambertian emitter)
- Color: Cx = 0.33, Cy = 0.34 acc. to CIE 1931 (● ultra white)
- Corrosion Robustness Class: 3B
- Qualifications: AEC-Q102 Qualified
- ESD: 8 kV acc. to ANSI/ESDA/JEDEC JS-001 (HBM, Class 3B)

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## Ordering Information

Type	Luminous Flux <sup>1)</sup> $I_F = 1000 \text{ mA}$ $\Phi_V$	Ordering Code
LUW HWQP-5N8N-ebvF46fcbB46-8E8H	280 ... 450 lm	Q65112A6099

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## Maximum Ratings

Parameter	Symbol		Values
Operating Temperature	$T_{op}$	min.	-40 °C
		max.	125 °C
Storage Temperature	$T_{stg}$	min.	-40 °C
		max.	125 °C
Junction Temperature	$T_j$	max.	150 °C
Junction Temperature for short time applications*	$T_j$	max.	175 °C
Forward Current $T_s = 25\text{ °C}$	$I_F$	min.	50 mA
		max.	1500 mA
Surge Current $t \leq 10\ \mu\text{s}$ ; $D = 0.005$ ; $T_s = 25\text{ °C}$	$I_{FS}$	max.	2500 mA
ESD withstand voltage acc. to ANSI/ESDA/JEDEC JS-001 (HBM, Class 3B)	$V_{ESD}$		8 kV
Reverse current <sup>2)</sup>	$I_R$	max.	200 mA

\* The median lifetime (L70/B50) for  $T_j = 175\text{ °C}$  is 100h.

## Characteristics

$I_F = 1000 \text{ mA}$ ;  $T_S = 25 \text{ }^\circ\text{C}$

Parameter	Symbol		Values
Chromaticity Coordinate <sup>3)</sup>	$C_x$	typ.	0.33
	$C_y$	typ.	0.34
Viewing angle at 50% $I_V$	$2\phi$	typ.	120 °
Forward Voltage <sup>4)</sup> $I_F = 1000 \text{ mA}$	$V_F$	min.	2.75 V
		typ.	3.05 V
		max.	3.75 V
Reverse voltage (ESD device)	$V_{R\text{ESD}}$	min.	45 V
Reverse voltage <sup>2)</sup> $I_R = 20 \text{ mA}$	$V_R$	max.	1.2 V
Real thermal resistance junction/solderpoint <sup>5)</sup>	$R_{\text{thJS real}}$	typ.	4.3 K / W
		max.	5.5 K / W
Electrical thermal resistance junction/solderpoint <sup>5)</sup> with efficiency $\eta_e = 30 \%$	$R_{\text{thJS elec.}}$	typ.	3.0 K / W
		max.	3.9 K / W

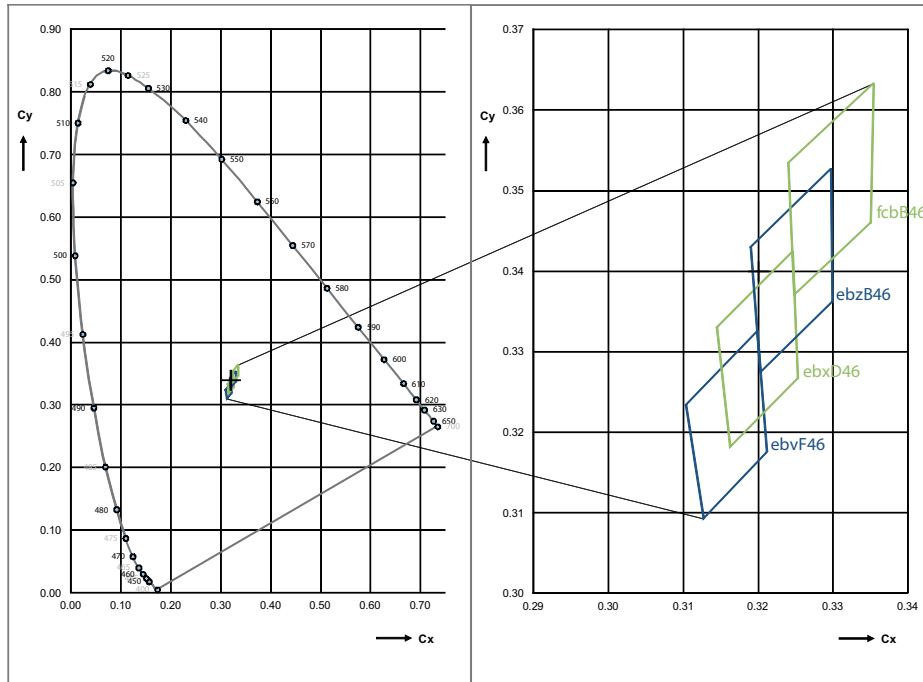
## Brightness Groups

Group	Luminous Flux <sup>1)</sup> $I_F = 1000 \text{ mA}$ min. $\Phi_V$	Luminous Flux <sup>1)</sup> $I_F = 1000 \text{ mA}$ max. $\Phi_V$	Luminous Intensity <sup>6)</sup> $I_F = 1000 \text{ mA}$ typ. $I_v$
5N	280 lm	315 lm	98 cd
N6	300 lm	315 lm	102 cd
6N	315 lm	355 lm	111 cd
N7	334 lm	355 lm	114 cd
7N	355 lm	400 lm	125 cd
8N	400 lm	450 lm	140 cd

## Forward Voltage Groups

Group	Forward Voltage <sup>4)</sup> $I_F = 1000 \text{ mA}$ min. $V_F$	Forward Voltage <sup>4)</sup> $I_F = 1000 \text{ mA}$ max. $V_F$
8E	2.75 V	3.00 V
8F	3.00 V	3.25 V
8G	3.25 V	3.50 V
8H	3.50 V	3.75 V

### Chromaticity Coordinate Groups <sup>3)</sup>



### Chromaticity Coordinate Groups <sup>3)</sup>

Group	Cx	Cy	Group	Cx	Cy
ebvF46	0.3127	0.3093	ebzB46	0.3203	0.3274
	0.3212	0.3175		0.3299	0.3361
	0.3199	0.3325		0.3298	0.3526
	0.3104	0.3234		0.3190	0.3430
ebxD46	0.3163	0.3181	fcbB46	0.3248	0.3370
	0.3253	0.3266		0.3350	0.3460
	0.3246	0.3424		0.3355	0.3633
	0.3145	0.3330		0.3241	0.3534

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## Group Name on Label

**Example: 5N-ebvF46-8E**

Brightness

Color Chromaticity

Forward Voltage

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5N

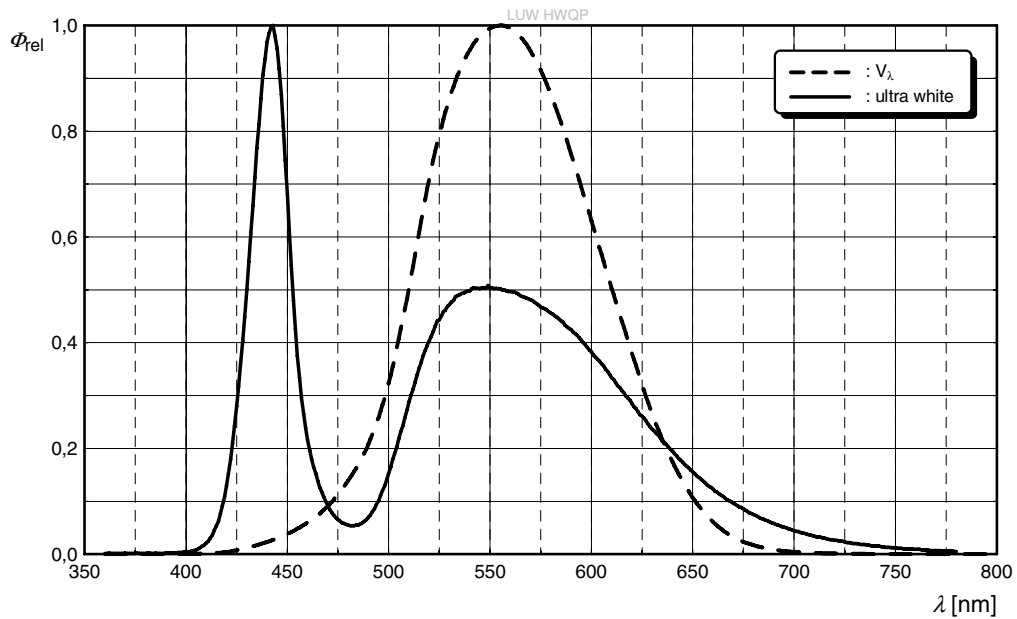
ebvF46

8E

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### Relative Spectral Emission <sup>6)</sup>

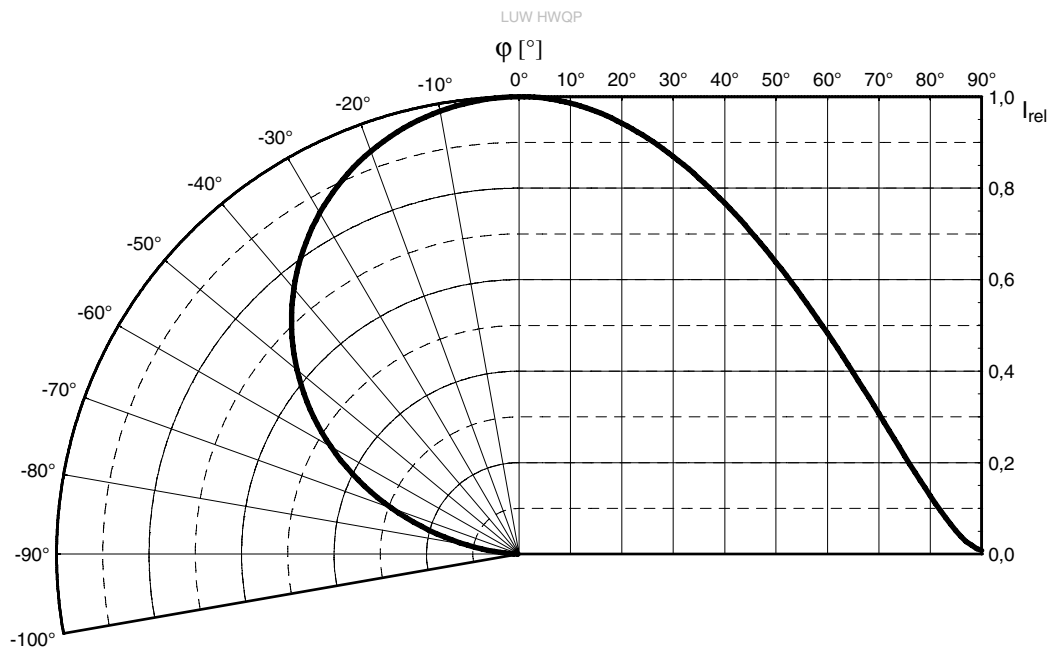
$\Phi_{rel} = f(\lambda); I_F = 1000 \text{ mA}; T_S = 25 \text{ }^\circ\text{C}$



Note: Percentage of red: >5% acc. to ECE regulation  
 Percentage of UV: <10-5 W/m acc. to ECE regulation

### Radiation Characteristics <sup>6)</sup>

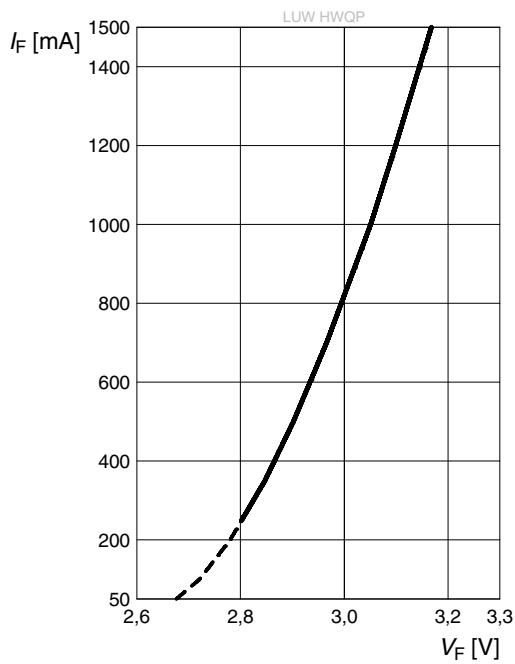
$I_{rel} = f(\phi); T_S = 25 \text{ }^\circ\text{C}$





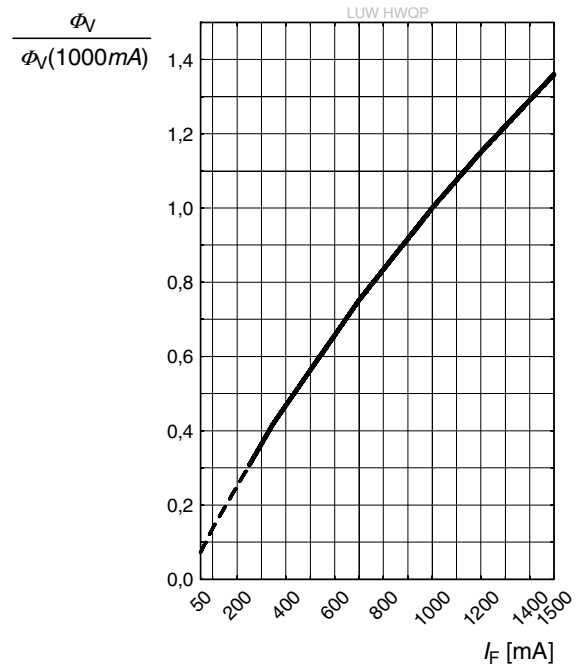
**Forward current** 6), 7)

$I_F = f(V_F); T_S = 25\text{ °C}$



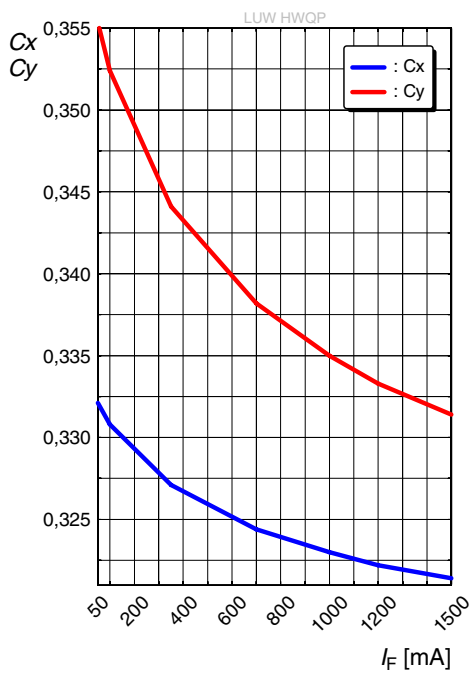
**Relative Luminous Flux** 6), 7)

$\Phi_V / \Phi_V(1000\text{ mA}) = f(I_F); T_S = 25\text{ °C}$



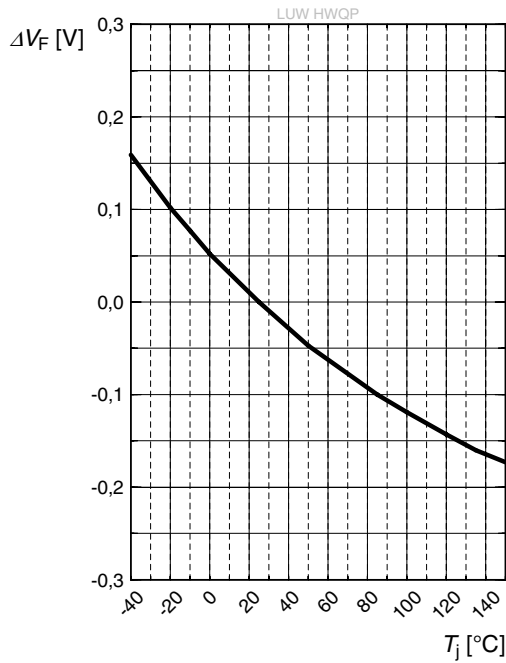
**Chromaticity Coordinate Shift** 6)

$C_x, C_y = f(I_F); T_S = 25\text{ °C}$



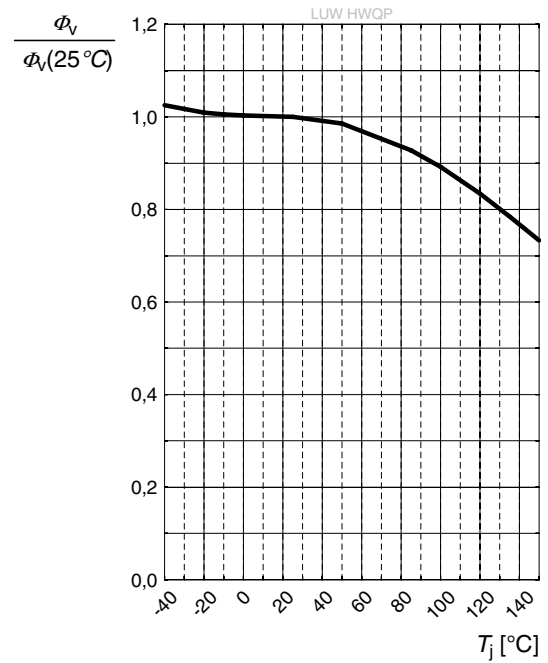
### Forward Voltage <sup>6)</sup>

$$\Delta V_F = V_F - V_F(25\text{ }^\circ\text{C}) = f(T_j); I_F = 1000\text{ mA}$$



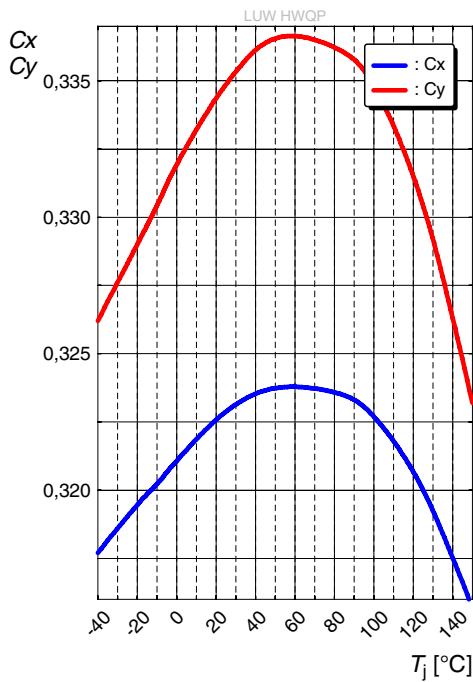
### Relative Luminous Flux <sup>6)</sup>

$$\Phi_V / \Phi_V(25\text{ }^\circ\text{C}) = f(T_j); I_F = 1000\text{ mA}$$



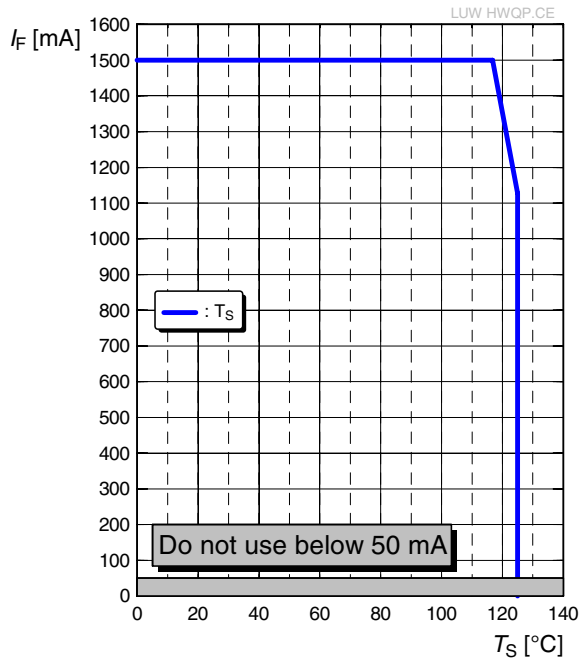
### Chromaticity Coordinate Shift <sup>6)</sup>

$$C_x, C_y = f(T_j); I_F = 1000\text{ mA}$$



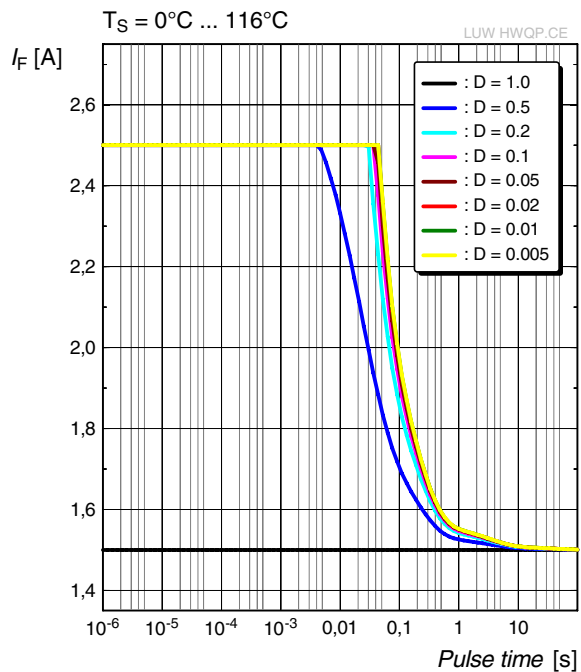
### Max. Permissible Forward Current

$I_F = f(T)$



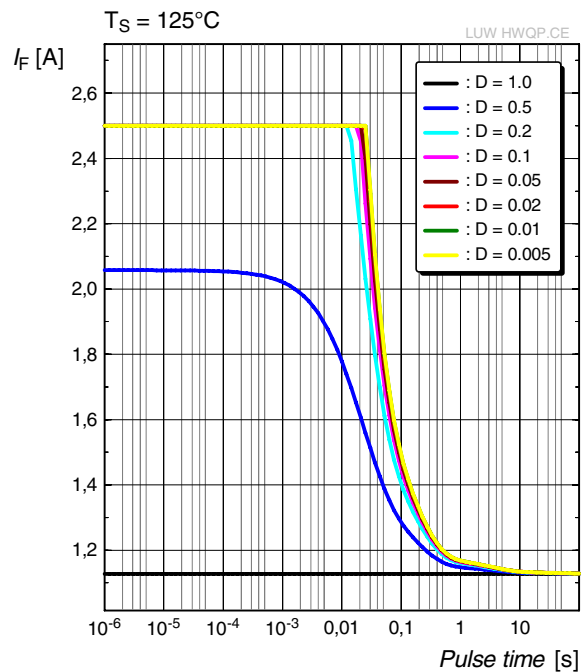
### Permissible Pulse Handling Capability

$I_F = f(t_p)$ ; D: Duty cycle

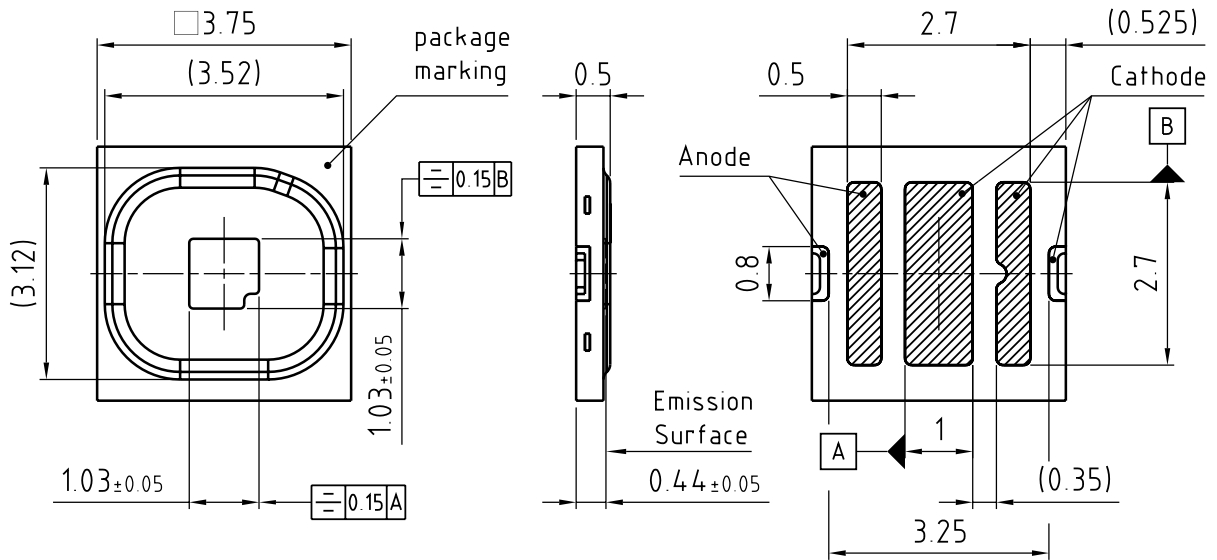


### Permissible Pulse Handling Capability

$I_F = f(t_p)$ ; D: Duty cycle



**Dimensional Drawing** <sup>8)</sup>



general tolerance ± 0.1  
 lead finish Au

C67062-A0081-A1-05

**Further Information:**

**Approximate Weight:** 23.0 mg

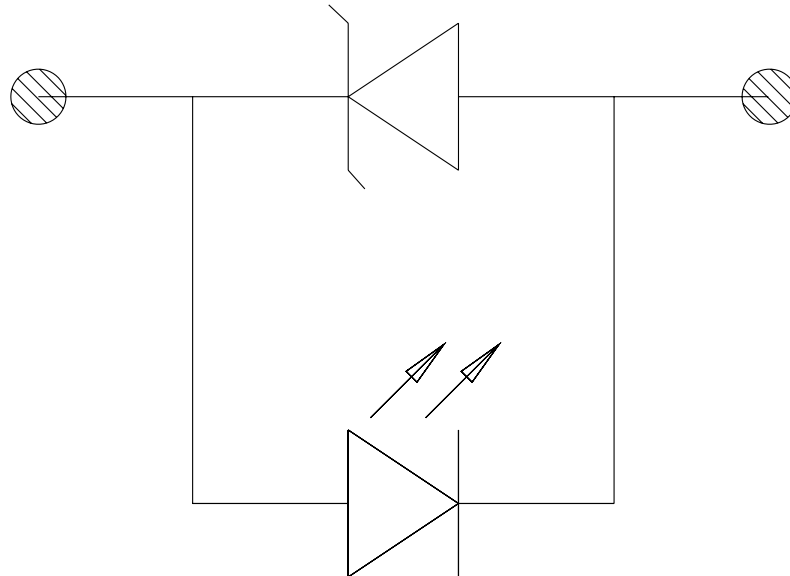
**Corrosion test:** Class: 3B  
 Test condition: 40°C / 90 % RH / 15 ppm H<sub>2</sub>S / 14 days (stricter than IEC 60068-2-43)

**ESD advice:** The device is protected by ESD device which is connected in parallel to the Chip.

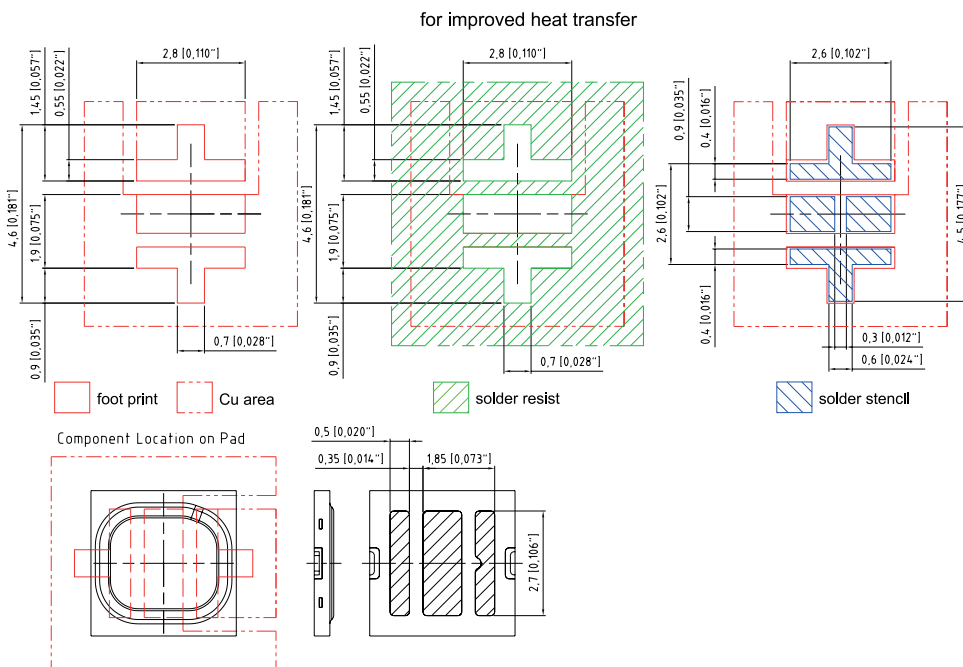
Electrical Internal Circuit

Anode

Cathode

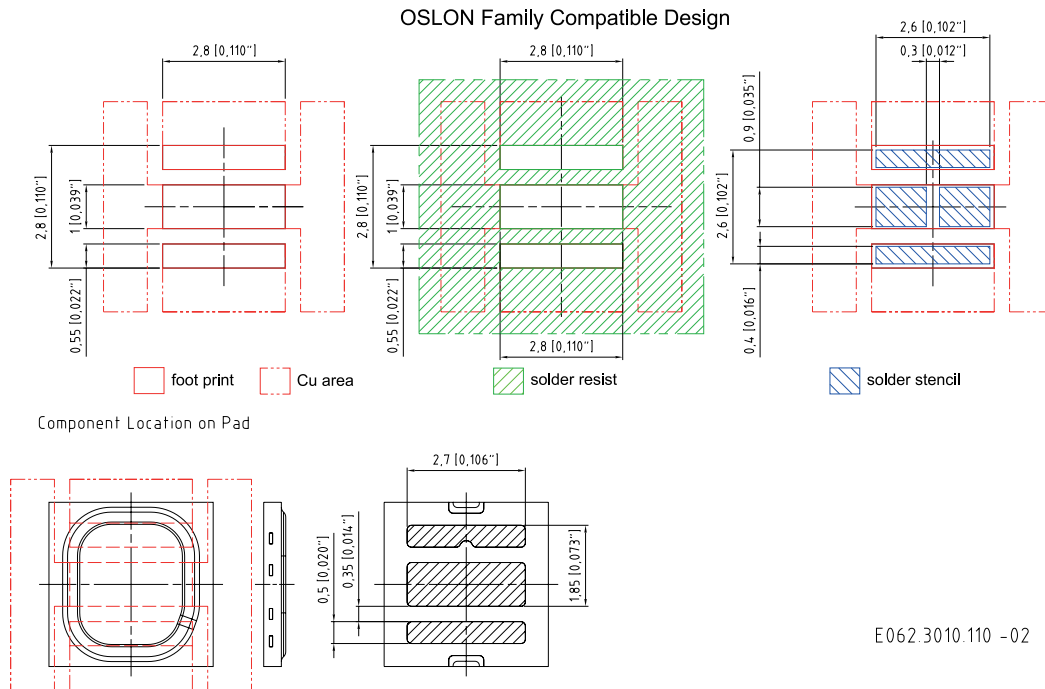


Recommended Solder Pad <sup>8)</sup>



E062.3010.107 -02

## Recommended Solder Pad <sup>8)</sup>

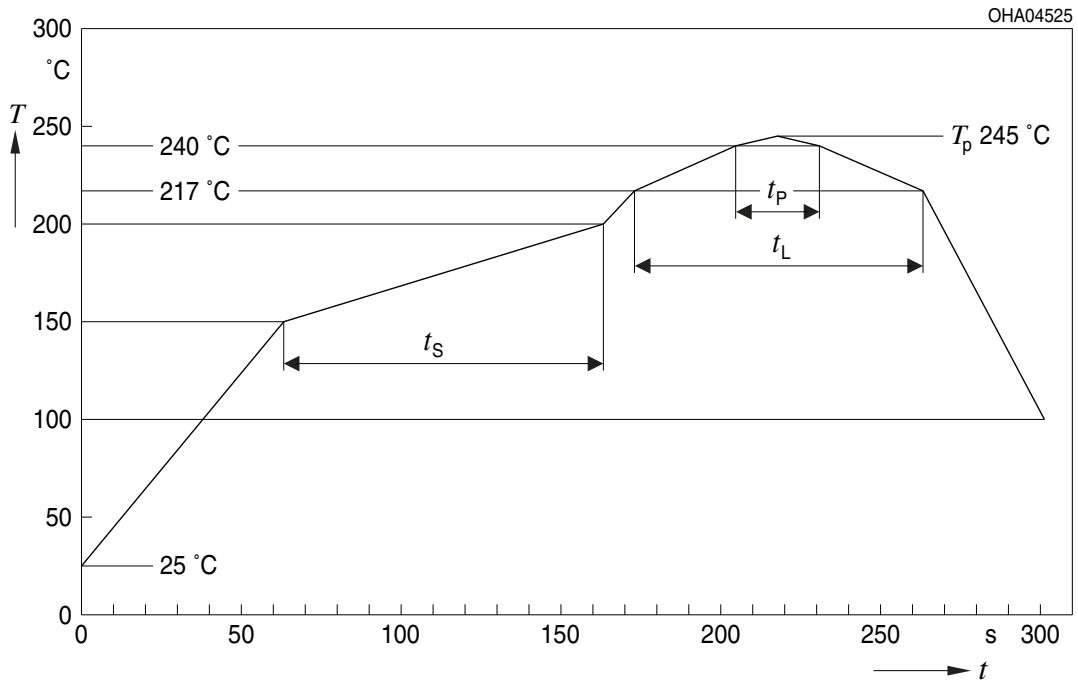


E062.3010.110 -02

For superior solder joint connectivity results we recommend soldering under standard nitrogen atmosphere. In case the PCB layout of the application is intended to be used with other OSLON derivatives or in future developed OSLON derivatives, the heat sink must not be electrically connected to anode or cathode solder pad because of possible chip inverted polarity. Package not suitable for ultra sonic cleaning. To ensure a high solder joint reliability and to minimize the risk of solder joint cracks, the customer is responsible to evaluate the combination of PCB board and solder paste material for his application.

## Reflow Soldering Profile

Product complies to MSL Level 2 acc. to JEDEC J-STD-020E

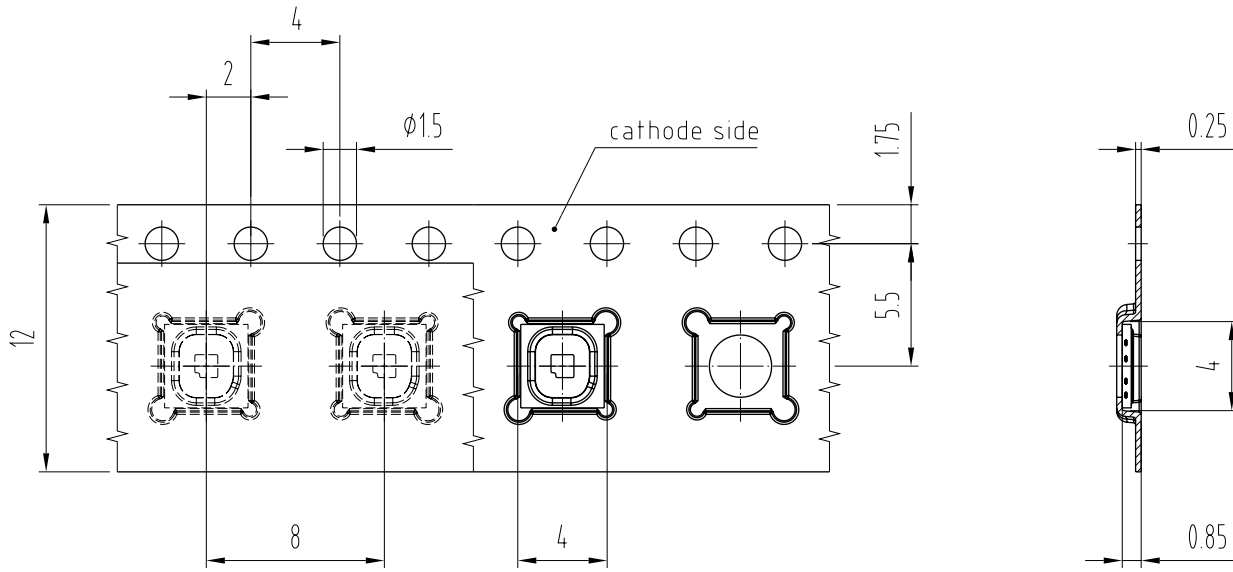


Profile Feature	Symbol	Pb-Free (SnAgCu) Assembly			Unit
		Minimum	Recommendation	Maximum	
Ramp-up rate to preheat <sup>*)</sup> 25 °C to 150 °C			2	3	K/s
Time $t_s$ $T_{Smin}$ to $T_{Smax}$	$t_s$	60	100	120	s
Ramp-up rate to peak <sup>*)</sup> $T_{Smax}$ to $T_p$			2	3	K/s
Liquidus temperature	$T_L$		217		°C
Time above liquidus temperature	$t_L$		80	100	s
Peak temperature	$T_p$		245	260	°C
Time within 5 °C of the specified peak temperature $T_p - 5$ K	$t_p$	10	20	30	s
Ramp-down rate* $T_p$ to 100 °C			3	6	K/s
Time 25 °C to $T_p$				480	s

All temperatures refer to the center of the package, measured on the top of the component

\* slope calculation  $DT/Dt$ :  $Dt$  max. 5 s; fulfillment for the whole T-range

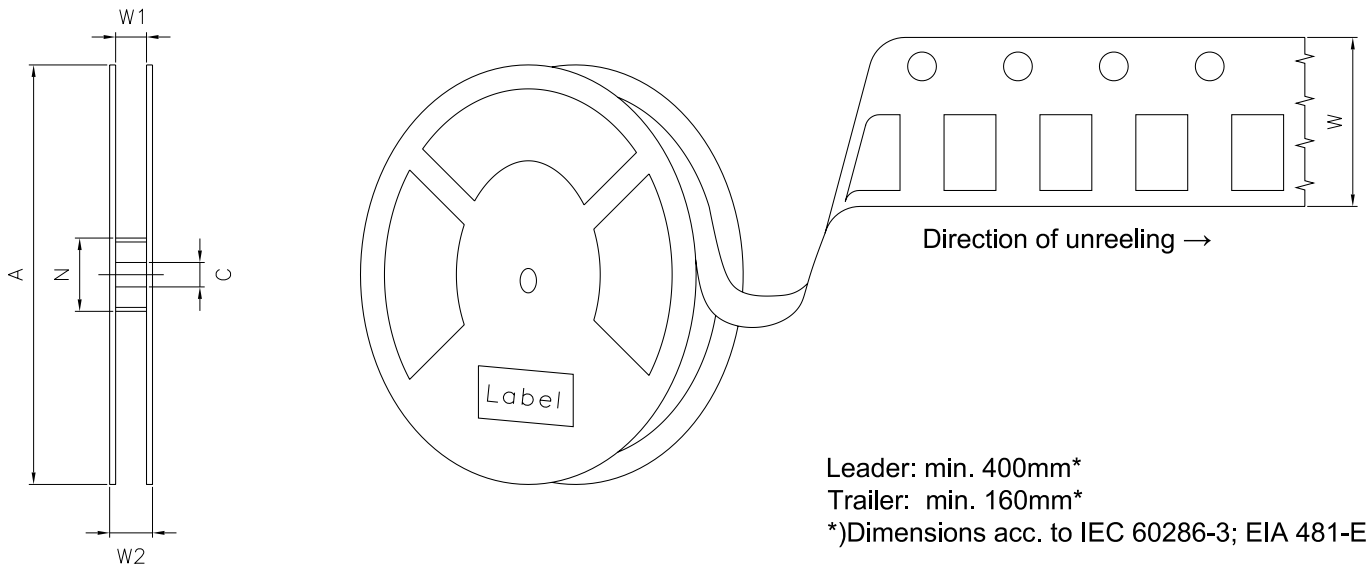
Taping <sup>8)</sup>



C63062-A4136-B10 -03



**Tape and Reel** <sup>9)</sup>



**Reel Dimensions**

A	W	N <sub>min</sub>	W <sub>1</sub>	W <sub>2max</sub>	Pieces per PU
180 mm	12 + 0.3 / - 0.1 mm	60 mm	12.4 + 2 mm	18.4 mm	2000

### Barcode-Product-Label (BPL)

**OSRAM Opto Semiconductors** LX XXXX BIN1: XX-XX-X-XXX-X

RoHS Compliant

(6P) BATCH NO: 1234567890 ML Temp ST  
X XXX °C X

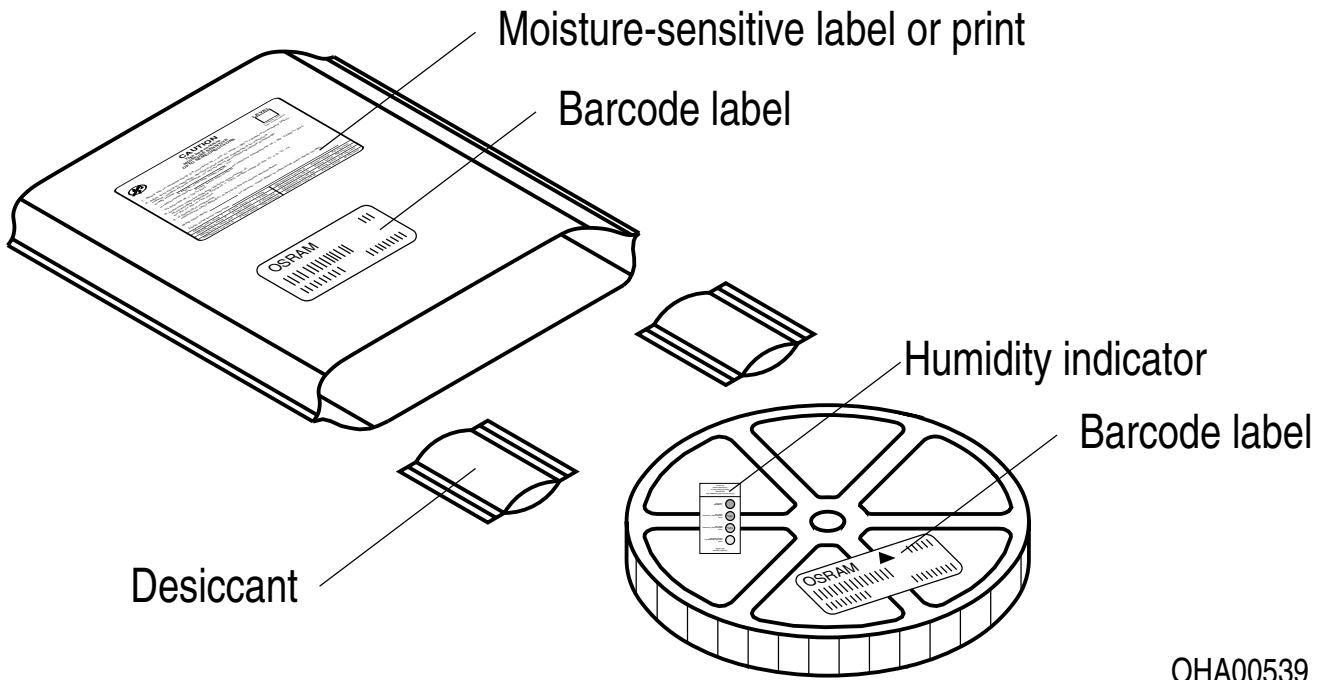
(1T) LOT NO: 1234567890 (9D) D/C: 1234 Pack: RXX  
DEMY XXX  
X\_X123\_1234.1234 X

(X) PROD NO: 123456789(Q)QTY: 9999 (G) GROUP: XX-XX-X-X

The diagram shows a rectangular label with rounded corners. It contains the OSRAM logo and name, a part number (LX XXXX), and a bin number (BIN1: XX-XX-X-XXX-X). It features three main barcode sections: a top barcode for batch number (6P), a middle barcode for lot number (1T), and a bottom barcode for product number (X). Text fields include RoHS Compliant, ML Temp ST (X XXX °C X), (9D) D/C: 1234, Pack: RXX, DEMY XXX, X\_X123\_1234.1234 X, and (Q)QTY: 9999. A QR code is located on the right side. A 'no moisture' symbol is also present.

OHA04563

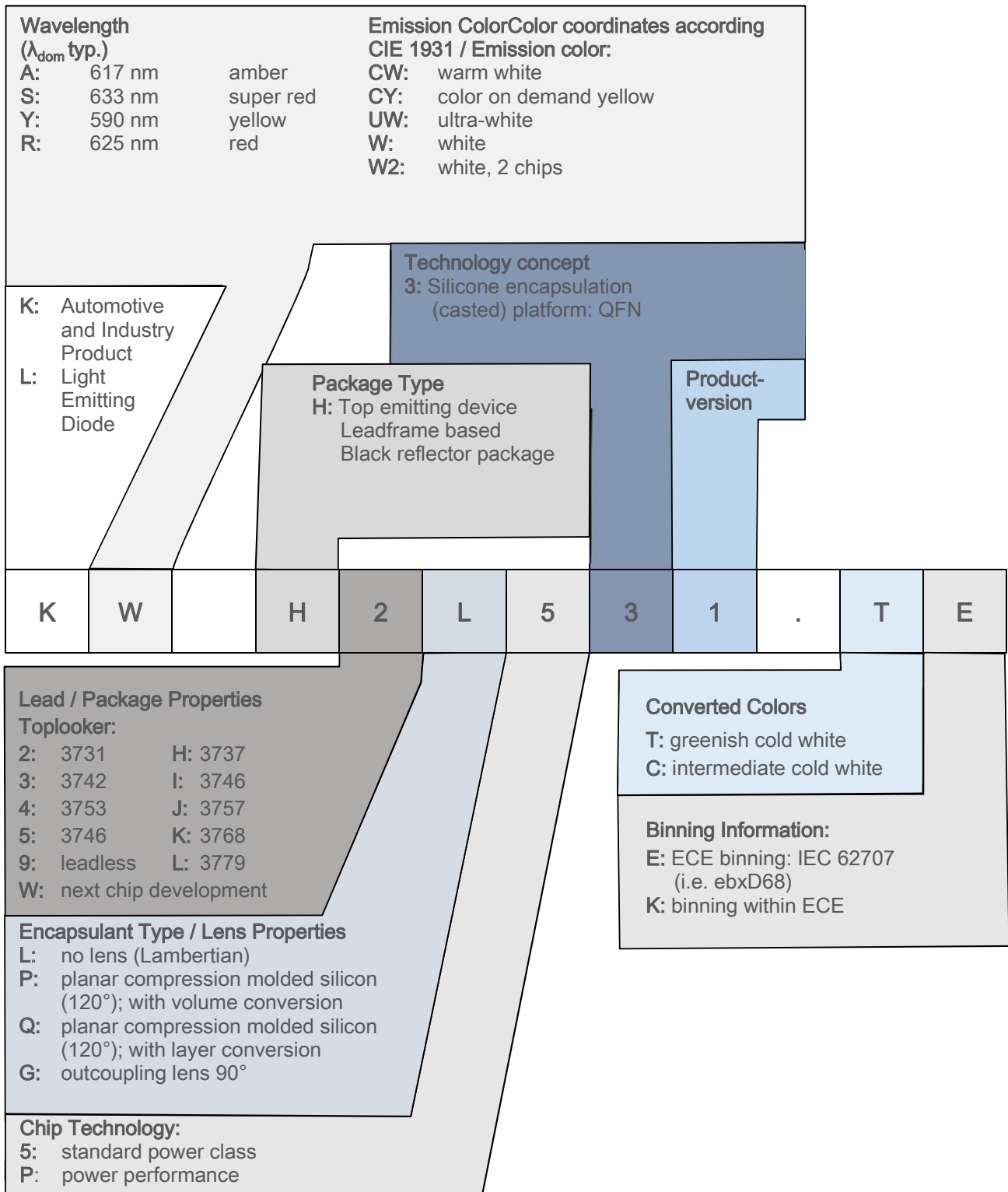
### Dry Packing Process and Materials <sup>8)</sup>



OHA00539

Moisture-sensitive product is packed in a dry bag containing desiccant and a humidity card according JEDEC-STD-033.

## Type Designation System



## Notes

The evaluation of eye safety occurs according to the standard IEC 62471:2006 (photo biological safety of lamps and lamp systems). Within the risk grouping system of this IEC standard, the device specified in this data sheet falls into the class **moderate risk (exposure time 0.25 s)**. Under real circumstances (for exposure time, conditions of the eye pupils, observation distance), it is assumed that no endangerment to the eye exists from these devices. As a matter of principle, however, it should be mentioned that intense light sources have a high secondary exposure potential due to their blinding effect. When looking at bright light sources (e.g. headlights), temporary reduction in visual acuity and afterimages can occur, leading to irritation, annoyance, visual impairment, and even accidents, depending on the situation.

Subcomponents of this device contain, in addition to other substances, metal filled materials including silver. Metal filled materials can be affected by environments that contain traces of aggressive substances. Therefore, we recommend that customers minimize device exposure to aggressive substances during storage, production, and use. Devices that showed visible discoloration when tested using the described tests above did show no performance deviations within failure limits during the stated test duration. Respective failure limits are described in the IEC60810.

For further application related information please visit [www.osram-os.com/appnotes](http://www.osram-os.com/appnotes)

## Disclaimer

### **Attention please!**

The information describes the type of component and shall not be considered as assured characteristics. Terms of delivery and rights to change design reserved. Due to technical requirements components may contain dangerous substances.

For information on the types in question please contact our Sales Organization.

If printed or downloaded, please find the latest version on the OSRAM OS website.

### **Packing**

Please use the recycling operators known to you. We can also help you – get in touch with your nearest sales office. By agreement we will take packing material back, if it is sorted. You must bear the costs of transport. For packing material that is returned to us unsorted or which we are not obliged to accept, we shall have to invoice you for any costs incurred.

### **Product and functional safety devices/applications or medical devices/applications**

OSRAM OS components are not developed, constructed or tested for the application as safety relevant component or for the application in medical devices.

OSRAM OS products are not qualified at module and system level for such application.

In case buyer – or customer supplied by buyer – considers using OSRAM OS components in product safety devices/applications or medical devices/applications, buyer and/or customer has to inform the local sales partner of OSRAM OS immediately and OSRAM OS and buyer and /or customer will analyze and coordinate the customer-specific request between OSRAM OS and buyer and/or customer.

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## Glossary

- 1) **Brightness:** Brightness values are measured during a current pulse of typically 25 ms, with an internal reproducibility of  $\pm 8\%$  and an expanded uncertainty of  $\pm 11\%$  (acc. to GUM with a coverage factor of  $k = 3$ ).
- 2) **Reverse Operation:** Reverse Operation of 10 hours is permissible in total. Continuous reverse operation is not allowed.
- 3) **Chromaticity coordinate groups:** Chromaticity coordinates are measured during a current pulse of typically 25 ms, with an internal reproducibility of  $\pm 0.005$  and an expanded uncertainty of  $\pm 0.01$  (acc. to GUM with a coverage factor of  $k = 3$ ).
- 4) **Forward Voltage:** The forward voltage is measured during a current pulse of typically 8 ms, with an internal reproducibility of  $\pm 0.05\text{ V}$  and an expanded uncertainty of  $\pm 0.1\text{ V}$  (acc. to GUM with a coverage factor of  $k = 3$ ).
- 5) **Thermal Resistance:**  $R_{th\ max}$  is based on statistic values ( $6\sigma$ ).
- 6) **Typical Values:** Due to the special conditions of the manufacturing processes of semiconductor devices, the typical data or calculated correlations of technical parameters can only reflect statistical figures. These do not necessarily correspond to the actual parameters of each single product, which could differ from the typical data and calculated correlations or the typical characteristic line. If requested, e.g. because of technical improvements, these typ. data will be changed without any further notice.
- 7) **Characteristic curve:** In the range where the line of the graph is broken, you must expect higher differences between single devices within one packing unit.
- 8) **Tolerance of Measure:** Unless otherwise noted in drawing, tolerances are specified with  $\pm 0.1$  and dimensions are specified in mm.
- 9) **Tape and Reel:** All dimensions and tolerances are specified acc. IEC 60286-3 and specified in mm.

## Revision History

Version	Date	Change
1.11	2020-01-30	Features Further Information Recommended Solder Pad Reel Dimensions Schematic Transportation Box Dimensions of Transportation Box Type Designation System Notes Disclaimer Glossary

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